CUC-SP-J1ST-S/R4LT-SMD - Modular RJ45 PCB connectors

1149611

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Modular RJ45 PCB connectors, 1x1 single-port, connection direction of the connector to the PCB: 180 °, Shielded, number of positions: 8, PoE++, SMT, SMD, Reflow, IP20, type of packaging: Tape and Reel

Your advantages

- The reflow capability enables efficient, cost-optimized processing
- The extended temperature range from -40 °C to +85 °C enables use in demanding applications

Commercial data

Item number	1149611
Packing unit	180 pc
Minimum order quantity	180 pc
Sales key	AB12
Product key	ABNADB
GTIN	4063151143848
Weight per piece (including packing)	6.022 g
Weight per piece (excluding packing)	4.63 g
Customs tariff number	85366930
Country of origin	TW

Technical data

Product properties

Slots	1x1 single-port
Orientation to PCB	180.00 °
Type	SMD
Connection profile	RJ45
Number of positions	8 (8P8C)
Type of locking	Snap-in locking
Shielding	Shielded
Processing notes	Reflow
Type of packaging	Tape and Reel
Power transmission	PoE++ (according to IEEE 802.3bt)
Power PSE	90 W (Class 8 in accordance with IEEE 802.3bt)
Power PD	71 W (Class 4 in accordance with IEEE 802.3bt)

Electrical properties

Pollution degree	2
Overvoltage category	I (IEC 60664-1)
Rated voltage	72 V DC
Rated surge voltage	1.5 kV DC (IEC 60664-1)
Rated current	1.5 A (IEC 60603-7)
Insulation resistance	> 500 MΩ (IEC 60603-7)
Test voltage (Contact/contact)	1.5 kV DC (IEC 60603-7)
Test voltage (Contact/shield)	1.5 kV DC (IEC 60603-7)

Dimensions

Length	14.5 mm
Width	16.1 mm
Height	13.2 mm
Installed height	13.20 mm

Material specifications

Material Contact carrier	PA
Flame resistance	UL 94 V0
Halogen-free	no
Material Housing	Copper alloy
Material Housing coating	Ni (0,508 µm / 20 µ")
Material Housing pin coating (top layer/selective)	Sn (1.27 µm/50 µ")
Material Contact	Phosphor bronze
Material Solder contact coating (intermediate layer)	Ni (1.27 µm/50 µ")
Material Solder contact coating (top layer/selective)	Au (Flash)
Material Plug contact coating (top layer/selective)	Au

Material Plug contact coating (intermediate layer)	Ni (1,270 µm min / 50 µ" min)

Mechanical properties

Mechanical data

Insertion/withdrawal cycles	> 750 (IEC 60603-7)
Insertion force	< 20 N (IEC 60603-7)
Withdrawal force	< 20 N (IEC 60603-7)

Environmental and real-life conditions

Ambient conditions

Ambient temperature (operation)	-40 °C ... 85 °C
Ambient temperature (storage/transport)	-40 °C ... 85 °C
Degree of protection (plugged in)	IP20 (IEC 60603-7)
Degree of protection (Not plugged in)	IP20 (IEC 60603-7)

Test specification for vibration - sine

Acceleration	50 m/s²
Amplitude	0.35 mm
Sweep speed	1 octave/min

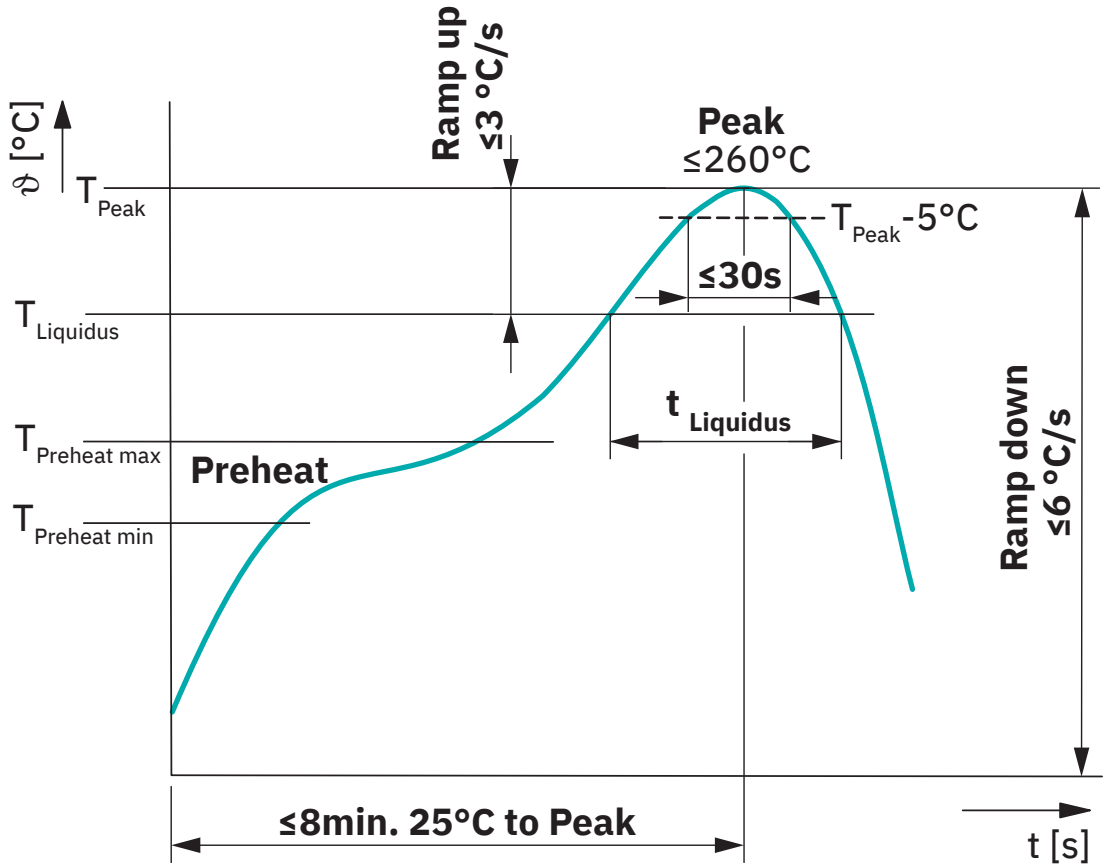
Mounting

Processing notes

Mounting type	SMT
Moisture Sensitive Level	MSL 1 (IEC 60068-2-58)
Solder cycles in the reflow	3 (IEC 60068-2-58)

Drawings

Diagram



Classification reflow soldering profile

Approvals

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cUL Recognized
Approval ID: FILE E 335024

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Classifications

ECLASS

ECLASS-13.0	27460201
ECLASS-15.0	27460201

ETIM

ETIM 10.0	EC002637

UNSPSC

UNSPSC 21.0	39121400

Environmental product compliance

EU RoHS

Fulfills EU RoHS substance requirements	Yes, No exemptions

China RoHS

Environment friendly use period (EFUP)	EFUP-E
	No hazardous substances above the limits

EU REACH SVHC

REACH candidate substance (CAS No.)	No substance above 0.1 wt%

EF3.1 Climate Change

CO2e kg	0.21 kg CO2e

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